V. 06/23

ADLINK
LEADING EDGE COMPUTING

Redefining Next-Generation Applications at the Edge

Evolving with Edge AI Computing Platforms

Alcom electronics
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Evolving with Edge AI Computing

The Ultimate Blend of Performance and Efficiency

ADLINK offers wide-ranging industrial computers and integration services for automation applications with various innovative technologies, including cloud computing (industrial and video servers), edge computing (fanless, slim, portable devices), and high-performance embedded systems. ADLINK's intelligent systems are equipped with smart, secure, energy-saving features, and are designed specifically for vertical markets in intelligent transportation, factory automation/machine automation, cloud infrastructure, and intelligent video application sectors.

Partner Collaboration for Extensive Edge Computing Platforms

ADLINK allies with leading industry partners — Intel, NVIDA, Arm, etc. — to provide up-to-date technologies and comprehensive product lines.

Thermal Optimization Design

Embedded Computers

Flexible Peripheral Module Integration

ADLINK provides a full range of modules for system integrations, including I/O expansion, AI acceleration modules, SSD, memory, and wireless module solutions, enabling clients to easily implement what they need into their solution.

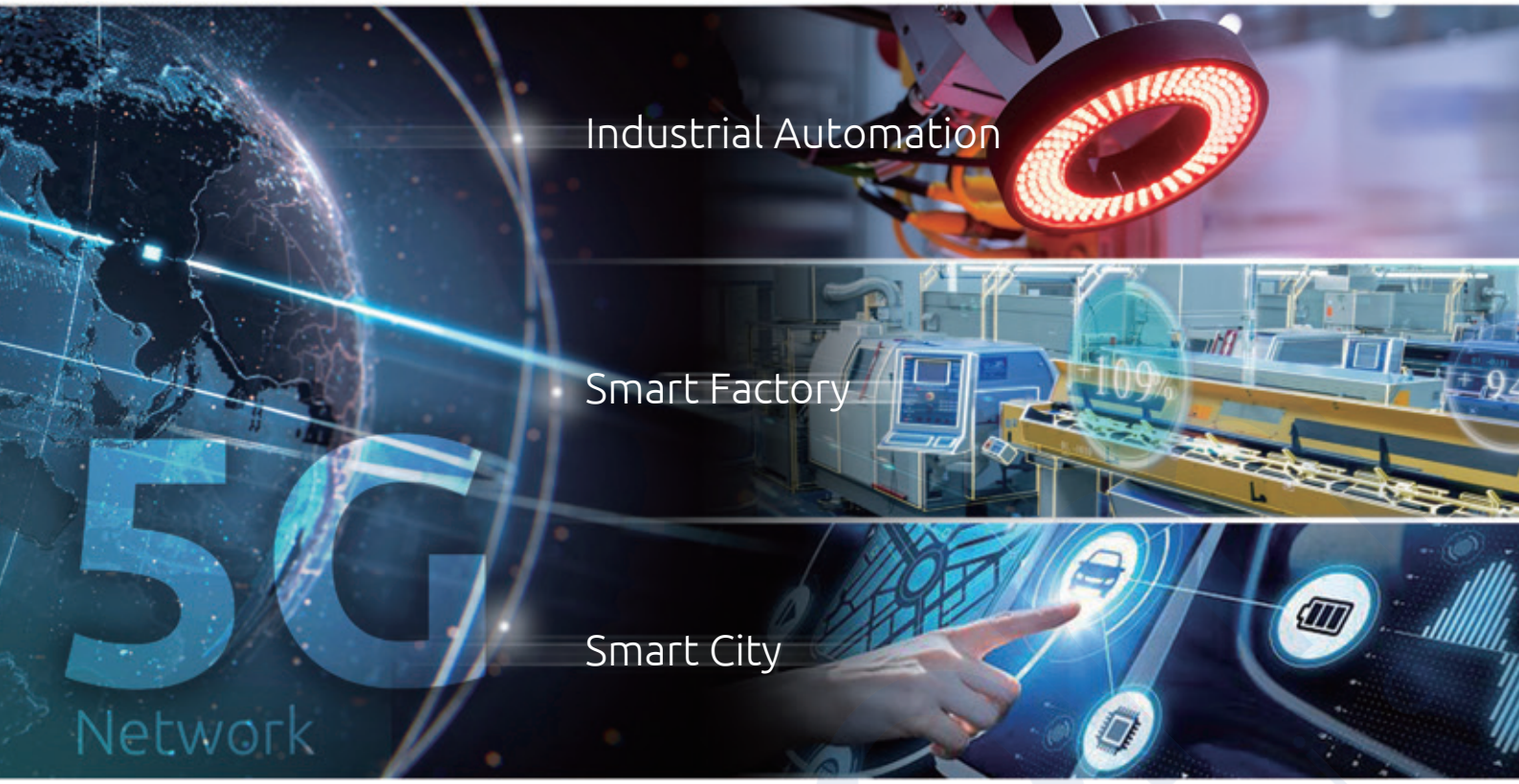
Complete AI Modules Support

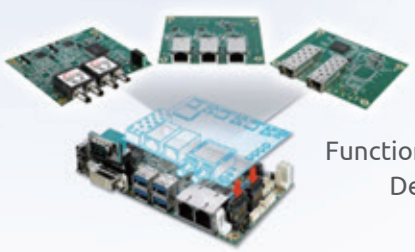
IoT Gateways

Optimized AI Solutions Development

ADLINK supplies flexible heterogeneous computing platforms with highly-integrated CPU, GPU, FPGA, and ASIC and helps users optimize their system architectures to fulfill their application and ROI objectives.

Configuration to Order Services




Function Modules
Design

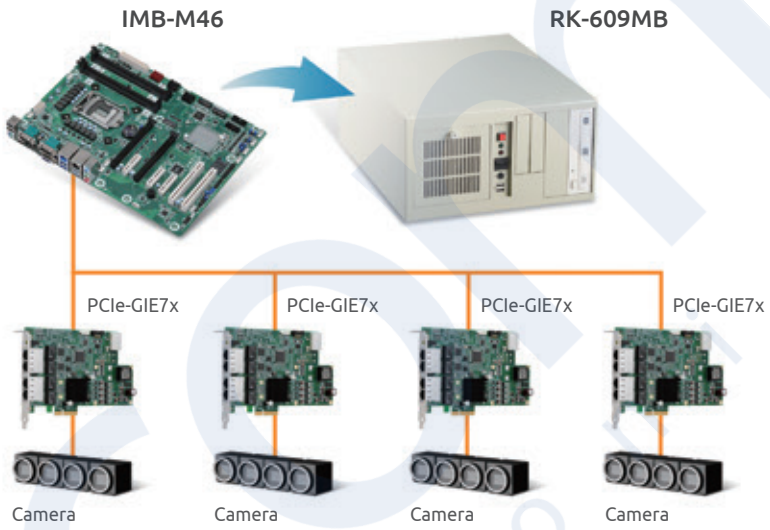

SSD, Wireless Modules

Cell Seal Welding Quality Inspection

Electric vehicles have exhibited phenomenal growth during the last few years. Battery manufacturers, whose batteries form critical components for EVs, are having to reassess their production systems to increase their output, by stepping up the pace of production and by increasing usable yield. In the back-end process of battery manufacturing, square batteries undergo two liquid injection procedures and need to be welded and sealed after completion. In preventing electrolyte leakage from collisions during battery use, it is necessary to perform defect detection on exploitation points, welding pits, holes, broken/missing welds, etc.

Solution Features

- High-performance Multi-Core CPU for image processing
- ADLINK added value : multiple frame grabber card/camera support
- Dedicate bandwidth for image capture
- ATX board with rugged I/O design to enhance I/O port compatibility and reliability

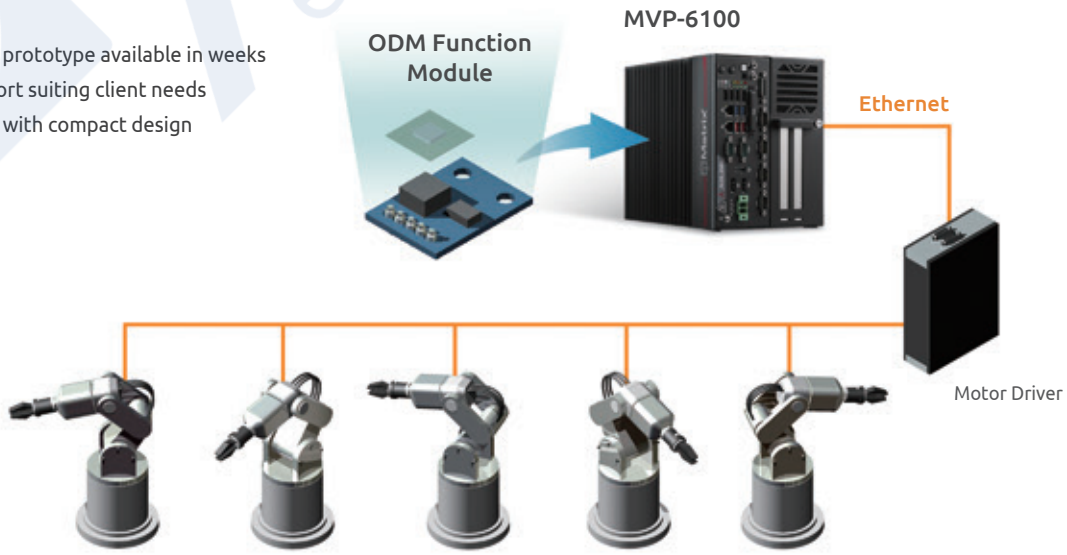


Industrial AI Controller System for Automated Packing Solutions

Leading Japanese brand in providing robotic solutions across varied industries, especially focusing on warehouse and packaging automation solutions. They are seeking a powerful contoller to update their robotics arms. Accordingly, ADLINK is collaborating with them to provide an automated packing solution that will be integrated into their new warehouse logistics system. Together with sorting personnel, it will be able to conduct fast, efficient cargo sorting to reduce the time between product sorting and shipping.

Solution Features

- Fast time to market, first prototype available in weeks
- Comprehensive I/O support suiting client needs
- Fitting into limited space with compact design



Applying AI Platform to Aquaculture for Improved Efficiency

As a global leader in shrimp product processing and exports, Minh Phu sees the potential gains in the deployment of IIoT (Industrial Internet of Things) and Industrial Automation 4.0, especially for large-scale management efficiency and detailed production yield analyses. Otanics Technology's Seafood Farming AI Monitoring System has used ADLINK DLAP-211-Nano Edge Inference Platform and industrial Modbus remote I/O modules as the hardware for their Shrimp Farm Management System.

Solution Features

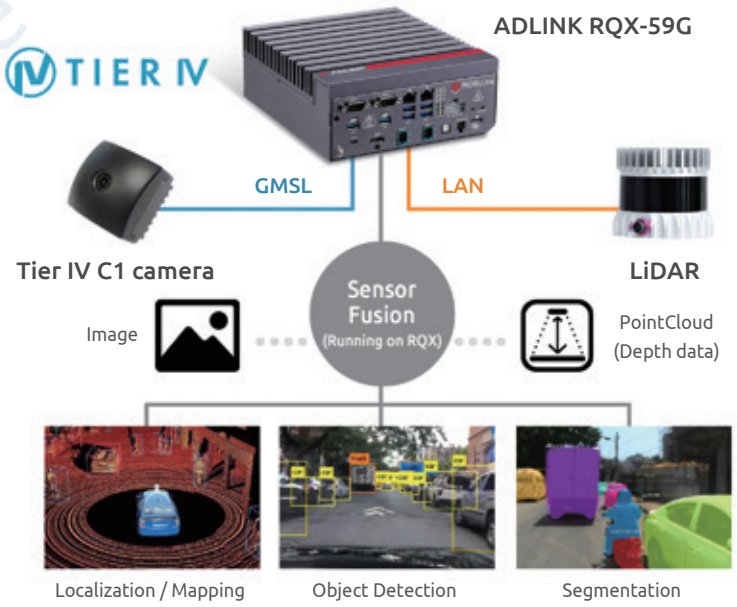
- Deep learning platform acceleration with high performance and improved energy efficiency
- Compact, durable, and fanless design for 24/7 operation even in the outdoors
- Wide temperature tolerance from -20°C to 70°C

Autonomous Driving for All

ADLINK, Tier IV, and AutoCore has made autonomous cars and robotics safer and more scalable with intelligent heterogeneous computing platforms and middleware. While ADLINK specializes in edge computing, Tier IV develops self-driving software, and AutoCore builds intelligent vehicle platforms. This collaboration unites edge AI technology, data-driven middleware, autonomous driving software, and heterogeneous computing to develop a broad range of next-gen autonomous driving applications. Together, this delivers scalable, high-performance, functional safety middleware on heterogeneous computing platforms for autonomous vehicles and mobile robotics.

Solution Features

- Partnership results in improved performance and reliability for autonomous driving systems.
- By incorporating ADLINK's reliable ROSCube controller, Tier IV's software can effectively enhance autonomous driving safety.
- The joint expertise ensures seamless integration of hardware and software components, simplifying the deployment of autonomous driving systems and reducing time-to-market.



Industrial Computers

The embedded market is now transitioning from the traditional fixed-function and isolated embedded systems to a new breed, offering vastly enhanced user experience while dramatically increasing the flow of information between cloud systems and data centers. ADLINK's intelligent computing platforms provide the core for intelligent systems, maximizing the flexibility of Intel processors, and at the same time enhancing productivity, safety, and efficiency.

Mini-ITX Embedded Boards

AmITX-CF-I

Mini-ITX Embedded Board with 8th/ 9th Gen Intel® Core™ i7/i5/i3 Processors

- 8th/9th Gen Intel® Core™ i7/i5/i3 and Intel® Pentium™/Celeron®
- Dual-channel DDR4 2400/2666 MHz non-ECC SODIMM memory up to 32 GB (dependent on CPU)
- DisplayPort, HDMI and DVI-D display outputs on rear IO

AmITX-AL-I

Thin Mini-ITX Embedded Board with Intel Atom® E3900 series, Pentium®, and Celeron® SoC

- Intel VT-x/VT-d supported
- Up to 16GB non-ECC DDR3L (1866/1600 MHz), 2X SO-DIMMs
- Intel® Gen9 Low Power graphics, up to 4k resolution, H.265 codec
- DisplayPort, HDMI, LVDS/eDP (optional) ports support three independent displays
- Operating temperature: -40°C to +85°C (optional)

Industrial ATX Motherboards

IMB-M47H

Industrial ATX Motherboard with 12th/13th Gen Intel® Core™ i9/i7/i5/i3 Processors

- Dual-channel DDR5 4800MHz (up to 64GB)
- 1x DP1.4a, 1x VGA, 1x HDMI 2.0b ports support three independent displays
- 2x GbE ports, 1x 1GbE (Intel? I219-LM), 1x 2.5GbE (Intel? I225-V)
- 1x PCIe x16 Gen5, 1x PCIe x4 Gen3, 1x PCIe x1 Gen3, 4x PCI
- TPM 2.0 onboard

IMB-M47

Industrial ATX Motherboard with 12th/13th Gen Intel® Core™ i9/i7/i5/i3 Processor

- 4x 288-pin Long-DIMM DDR5 4400 MHz, up to 128GB
- 1 x PCIe x16 (Gen5), 1 x PCIe x8 (Gen5), 2 x PCIe x4 (Gen4), 3 x PCIe x1 (Gen3), 1 x USB3.2 Gen2x2 Type C
- 5 x USB3.2 Gen2, 6 x USB 2.0
- 1 x M.2 Key B, 1 x M.2 Key E, 1 x M.2 Key M, 6 x COM, 8 x SATA3
- 1 x HDMI 2.0b, 1 x DP1.4a, 1 x VGA, supports Triple display
- 3x Intel 2.5 Gigabit LAN
- Supports Intel® vPro, AMT, VMD
- ATX PWR (8+24 Pin)

IMB-M46

Industrial ATX Motherboard with 10th Gen Intel® Core™ i9/ i7/ i5 /i3 Processor

- Dual-channel DDR4, up to 128GB
- 1x DP1.2, 1x VGA and 1x HDMI 2.0a supports Triple display
- 2xl GbE ports: 1x Intel 1GB, 1 x Intel 2.5GB
- 1x PCIe x16 Gen3, 1x PCIe x8 Gen3, 3x PCIe x4 Gen3, 2x PCI
- TPM 2.0 onboard

PICMG Single Board Computers

NuPRO-E47

PICMG® 1.3 Full-size LGA1700 with 12th/13th Gen Intel® Core™ i9/i7/i5/i3 Processor-based SHB

- Intel® Q670E Express chipset supporting PCIe Gen 3
- 2x DIMM sockets for up to 64GB (Non-ECC DDR5, 4800MHz)
- 6x SATA 3.0 onboard with RAID support
- 4x COM ports (including RS-232/422/485)
- Intel® PCIe bifurcation support

Industrial Computer Chassis

RK-609B Series

Wallmount Industrial Chassis supports 10-slot Backplane

- Supports 10 slot PICMG backplane
- Two 5.25” and two 3.5” external drive bays, one internal 3.5” drive bay
- Upper cover with captive screw
- Replaceable and easy-to-clean air filter
- 12cm cooling fan (93CFM)
- Two USB Type A and one PS/2 keyboard connectors on front panel

RK-609MB Series

Wallmount Industrial Chassis for ATX Industrial Motherboard

- Supports Mini-ITX, microATX, ATX industrial motherboards
- One 5.25”, two 3.5” external drive bays and one internal 3.5"
- or 2.5" drive bay
- Two USB type A connectors on front panel
- 12cm cooling fan (93 CFM)
- PS2 ATX power supply

RK-620 Series

4U Rack Mounted Industrial Chassis with 14-slot Backplane and Motherboard

- EIA RS-310C 19” rack mount standard
- Supports 14-slot backplane and ATX motherboard
- Two 5.25” external, one 3.5” external and one 3.5” internal drive bay
- Two USB ports inside front I/O
- Replaceable, easy-to-clean air filter
- PS2 ATX power supply

RK-410FS Series

4U Rackmount Industrial Chassis with 14-slot Backplane

- EIA RS-310C 19" rackmount standard
- 17.8 inch (451 mm) short depth
- Three 5.25" and one 3.5" shock-resistant drive bays
- Two front accessible USB connectors
- Adjustable hold down bar for cards
- Supports various backplanes and power supply units

RK-110S Series

1U Rackmount Industrial Chassis supports 3-slot Backplane

- 1U height, 17.7 inch (450 mm) short depth
- One slim FDD & one slim-type optical drive bay
- One rear PCI expansion slot, integrated 300 W power supply
- Supports PICMG 1.0 backplane and PICMG 1.3 backplane

Passive Backplanes

EBP-9E2

1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 6 PCI™ Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 6 PCI™
- Support ATX power supplies
- Dimension: 328 mm x 206 mm

EBP-13E2

1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 10 PCI™ Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 10 PCI™
- Support ATX power supplies
- Dimension: 330 mm x 318 mm

EBP-13E4

1 PICMG® CPU, 1 PCI-E® x16, 3 PCI-E® x4, 7 PCI™ Slots Backplane

- Segment: 1
- Slots:1 PICMG® CPU, 1 PCI-E® x16, 3 PCI-E® x4, 7 PCI™
- Support ATX power supplies
- Dimension: 330 mm x 318 mm

EBP-9E5

1 PICMG® CPU, 1 PCI-E® x16, 4 PCI-E® x1, 3 PCI™ Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x16, 4 PCI-E® x1, 3 PCI™
- Support ATX power supplies
- Dimension: 244 mm x 348 mm

EBP-D3E1

1 PICMG® CPU, 1 PCI-E® x4 Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x4
- Support ATX power supplies
- Dimension: 331 mm x 39 mm

EBP-7E2

1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 4 PCI™ Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 4 PCI™
- Support ATX power supplies
- Dimension: 328 mm x 206 mm

EBP-10E5

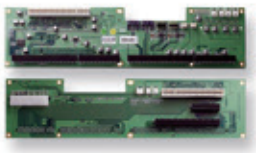
1 PICMG® CPU, 1 PCI-E® x16, 4 PCI-E® x1, 4 PCI™ Slots Backplane

- Segment: 1
- Slots:1 PICMG® CPU, 1 PCI-E® x16, 4 PCI-E® x1, 4 PCI™
- Support ATX power supplies
- Dimension: 330 mm x 318 mm

EBP-5E1

1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-X™, 2 PCI™ Slots Backplane

- Segment: 1
- Slots:1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-X™, 2 PCI™
- Support ATX power supplies
- Dimension: 153 mm x 330 mm



EBP-D5E2

1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x 4, 2 PCI™ Slots Backplane

- Segment: 1
- Slots: 1 PICMG® CPU, 1 PCI-E® x16, 1 PCI-E® x4, 2 PCI™
- Support ATX power supplies
- Dimension: 331 mm x 84 mm

Industrial-Grade SSDs

ADLINK's industrial solid state drives deliver dependable performance, efficient responsiveness and long usage life to accomplish mission-critical tasks. They are built to withstand rigorous operating environments. ADLINK SSDs come in different form factors such as 2.5" SSDs, M.2 embedded modules, and U.2 NVMe, for industrial applications. Reliable performance can be ensured, and in varied conditions, with ADLINK's industrial SSDs. They deliver high capacities and industrial temperature options in various small form factors.

Industrial-Grade SSDs

NEW

ASD+S7T Series

2.5" SATA SSD for Industrial Embedded Applications

- Advanced Flash Management, static and dynamic wear leveling, bad block management, TRIM, SMART, over-provision, and firmware update
- TCG OPAL-activated SSD supports PSID
- Low Power Management including DEVSLP mode (optional) and DIPM/HIPM mode
- Operating temperature range: -25°C to 85°C
- MTBF of more than 3,000,000 hours
- Vibration and shock resistance
- RoHS compliant

NEW

ASD+S2D Series

2.5" SATA SSD for Industrial Embedded Applications

- Advanced Flash Management, static and dynamic wear leveling, bad block management, TRIM, SMART, over-provision, and firmware update
- TCG OPAL-activated SSD supports PSID
- Low Power Management including DEVSLP mode (optional) and DIPM/HIPM mode
- Operating temperature range:
  C-grade : 0°C to 70°C / I-grade : -40°C to 85°C
- Hardware Power Loss Protection (HW PLP)
- MTBF of more than 1,500,000 hours
- Vibration and shock resistance
- RoHS compliant

NEW

ASD+S7T Series

M.2 2280 SATA SSD for Industrial Embedded Applications

- Advanced Flash Management, static and dynamic wear leveling, bad block management, TRIM, SMART, over-provision, and firmware update
- Low Power Management DEVSLP mode (optional) and DIPM/HIPM mode
- Operating temperature range: -25°C to 85°C
- MTBF of more than 3,000,000 hours
- Vibration and shock resistance
- RoHS compliant

NEW

ASD+E3T Series

M.2 2280/2242 PCIe Gen3 x4 SSD for Industrial Embedded Applications

- Advanced Flash Management, static and dynamic wear leveling, bad block management, TRIM, SMART, over-provision, and firmware update
- Low Power Management including DEVSLP mode (optional) and DIPM/HIPM mode
- TCG OPAL 2.0 with Physical Presence SID (PSID)
- Operating temperature range:
  E-grade -25°C to 85°C / I-grade -40°C to 85°C
- MTBF of more than 2,000,000 hours
- Vibration and shock resistance
- RoHS compliant

NEW

ASD+E2D Series

U.2 PCIe Gen3 x4 SSD for Industrial Embedded Applications

- Advanced Flash Management, static and dynamic wear leveling, bad block management, TRIM, SMART, over-provision, and firmware update
- Thermal Throttling to keep the optimal performance in the safe range of the temperature
- TCG OPAL 2.0 with Physical Presence SID (PSID)
- Operating temperature range:
  C-grade 0°C to 70°C / I-grade -40°C to 85°C
- MTBF of more than 2,000,000 hours
- Vibration and shock resistance
- RoHS compliant

Intelligent Embedded Computers

The Matrix series fanless, embedded computers enhance the responsiveness and durability of edge AI and edge computing applications. Designed to perform and to last, they enable timely data-driven decision making at the edge, improved efficiency and productivity, as well as security enhancement across industries.

Expandable Modular Industrial Computers

MVP-6200 Series

12th Gen Intel® Core™ i9/ i7/ i5/ i3 Expandable Fanless Computers

- Microsoft® Windows® or Linux® Ubuntu OS option
- Rugged, -20°C to 60°C fanless design for 24/7 operation
- Scalable with ADLINK Adaptive Function Module slot
- Flexible modular expansion support

MVP-6100-MXM Series

9th Gen Intel® Xeon®/Core™ i7/i5/i3 Expandable Fanless GPU/ AI Platforms

- 2x DDR4 SO-DIMM sockets, up to 32GB
- Up to 4x displays, DP 1.4 from MXM, 2x DP++, DVI, VGA
- 3x GbE, 3x COM, TPM2.0
- 2x USB 3.1 Gen 2, 1x USB 3.1 Gen 1, 3x USB 2.0
- Up to 4x 2.5" SATA, M.2 2280 storage options
- PCI, PCIe , Mini PCIe, M.2 3042, 2x USIM
- World leading embedded GP/GPU computing options built-in

MVP-6100 Series

9th Gen Intel® Xeon® /Core™ i7/i5/i3 & 8th Gen Celeron® Expandable Fanless Computers

- 2x DDR4 SO-DIMM sockets, up to 32GB
- 2x DP++/ DVI/ VGA/ 3x GbE/ 4x COM/ 8x DI/DO /TPM2.0
- 2x USB 3.1 Gen2 + 1x USB 3.1 Gen1 + 3x USB 2.0
- Up to 4x 2.5" SATA, CFast, M.2 2280
- Mini PCIe/ M.2 3042/ 2x USIM

Compact Modular Industrial Computers

MVP-5200 Series

12th Gen Intel® Core™ i3/ i5/ i7/ i9 Compact Fanless Computers

- Microsoft® Windows® or Linux® Ubuntu OS option
- Rugged, -20°C to 60°C fanless design for 24/7 operation
- Scalable with ADLINK AFM (Adaptive Function Module) slot

MVP-5100-MXM Series

9th Gen Intel® Core™ i7/i5/i3 Compact Fanless GPU/AI Platforms

- 2x DDR4 SO-DIMMs sockets, up to 32GB
- Up to 4x displays, DP 1.4 from MXM, 2x DP++, DVI, VGA,
- 3x GbE, 3x COM, TPM2.0
- 3x USB 3.1 Gen 1, 3x USB 2.0
- 2x 2.5" SATA, M.2 2280
- Mini PCIe, M.2 3042, 2x USIM

MVP-5100 Series

9th Gen Intel® Core™ i7/i5/i3 & 8th Gen Celeron® Compact Fanless Computers

- 2x DDR4 SO-DIMMs, up to 32GB
- 2x DP++/ DVI/ VGA/ 3x GbE/ 4x COM/ 8x DI/DO / TPM2.0
- 2x USB3.1 Gen2 + 1x USB3.1 Gen1 + 3x USB2.0
- 2x 2.5" SATA, CFast, M.2 2280
- Mini PCIe/ M.2 3042/ 2x USIM

Configurable Fanless Embedded Computers

MXC-6600 Series

9th Gen Intel® Xeon®/Core™ i7/i3 & 8th Gen Intel® Core™ i5 Configurable Fanless Computers

- 2x DDR4 (ECC) SO-DIMMs
- 2x DP++, 1x HDMI, 2x GbE, 6x COM, 8x DI/8x DO, TPM 2.0
- 2x USB 3.1 Gen2, 2x USB 3.1 Gen1, 4x USB 2.0
- up to 4x 2.5" SATA (RAID 0/1/5/10), CFast
- 1x Mini PCIe, M.2 2280/3042

MXC-6400 Series

6th Generation Intel® Core™ i7/i5/i3 Configurable Fanless Computers

- 2x DDR4 SO-DIMM sockets, up to 32GB
- 1 PCI + 2 PCIe x8 or 1 PCIe x16 slots
- 3x independent displays, 2x DP, 1x DVI-I
- 3x GbE, 4x COM, isol. 16x DI/16x DO, 6x USB3.0
- 2x 2.5" hot-swappable SATA III trays , 2x internal (RAID 0/1/5/10)
- 2x Mini PCIe

MXC-2300 Series

Intel® Atom™ processor E3845 Configurable Fanless Computers

- 2x DDR3L SO-DIMM, up to 8GB
- 2 PCI + 1 PCIe x4 or 3 PCI slots
- Built-in 2x isol. CAN, isol. 16x DI/16x DO
- 1x DP, 1x DVI-I
- VGA, 1x Mini PCIe, CFast, 1x 2.5" SATA
- 2x GbE, 1x USB 3.0, 4x USB 2.0
- 2x RS-232/422/485, 2x RS-232

Integrated Fanless Embedded Computers

MXE-5600 Series

9th Gen Intel® Xeon®, Core™ i7/i3 & 8th Gen Intel® Core™ i5 Integrated Fanless Embedded Computers

- 2x DDR4 SO-DIMMs, up to 32GB
- 2x DP++, HDMI, 2x GbE, 6x COM, 8x DI/ 8x DO, TPM2.0
- 2x USB 3.1 Gen2, 2x USB 3.1 Gen1. 4x USB 2.0
- 2x 2.5" SATA 6 Gb/s, CFast
- Mini PCIe, 3042, 2x USIM
- Expandable function module reserved

MXE-1500 Series

Intel® Celeron® N3160/ N3060 SoC Integrated Fanless Computers

- 2x DDR3L SO-DIMM, up to 8GB
- DP, VGA and optional LVDS or DP
- 3x GbE, up to 4x RS-232/422/485, 2x RS-232
- 4x DI/ 4x DO, TPM2.0, 2x USB3.0, 4x USB2.0
- 1x 2.5" SATA, CFast, Mini PCIe

MXE-210 Series

Intel Atom® Processor E3900 Ultra Compact Embedded Platforms

- 1x DP, 2x GbE, 2x RS-232/422/485
- 2x Mini PCIe, 1x mSATA, 1x Micro SD
- 1x 2.5" SATA or isolated 8x DI/ 8x DO
- TPM2.0, 2x USB3.0, 2x USB2.0
- eSIM support (Optional)

IoT Gateways

Coming Soon

MXA-200 Series

NXP i.MX8M Plus Quad-core Processor-based IIoT Gateway Platform

- NXP i.MX8M Plus Cortex A53 Quad-core 1.6GHz
- DDR4 2GB RAM, 32GB eMMC for system storage
- 2x RS-232/422/485 isolated serial ports
- 2x 10/100/1000 Ethernet ports
- 1x M.2 E-key for Wi-Fi, 1x M.2 B-key for 5G or 4G/LTE
- -20°C to 70°C operating temperature

MXE-210 Series

Intel Atom® Processor E3900 Ultra Compact IIoT Gateway Platforms

- 1x DP, 2x GbE, 2x RS-232/422/485
- 2x Mini PCIe, 1x mSATA, 1x Micro SD
- 1x 2.5" SATA or isolated 8x DI/ 8x DO
- TPM2.0, 2x USB3.0, 2x USB2.0
- eSIM support (Optional)

Edge AI Platforms

ADLINK's Edge AI platforms integrate hardware acceleration in deep learning (DL) workloads, offer exceptional performance per watt and per dollar, reliable end-to-end connectivity to break down information, and industrial environmental compliance for 24/7 operation.
They can generate the actionable intelligence required to achieve operational improvements, performance boost, and efficiency gains in manufacturing, transportation, medical, gaming, defense, smart city, retail applications and more.

NVIDIA Jetson Edge AI Platforms

DLAP-211 Series

Edge AI Platform Powered by NVIDIA® Jetson Xavier™ NX/ TX2 NX/ Nano™/ Orin™ NX / Orin™ Nano

- Linux® Ubuntu operating system
- High performance yet energy efficient
- Wide operating temperature range
- Compact, durable and fanless design
- Variety of industrial I/O ports and visual inferencing capabilities
- Support 24/7 secure remote control, device management, and monitoring

DLAP-401-Xavier

Edge AI Inference Platform Powered by NVIDIA® Jetson AGX Xavier™

- Linux® Ubuntu operating system
- High performance yet energy efficient
- Support wide operating temperature
- Compact, durable and fanless design
- Variety industrial I/O ports and visual inferencing capabilities
- Support 24/7 secure remote control, device management, and monitoring

DLAP-201-JT2

Edge AI Inference Platform Powered by NVIDIA® Jetson™ TX2

- Deep learning acceleration with NVIDIA® Jetson™ TX2
- Compact, durable and fanless design
- Wide operating temperature range
- Support 24/7 secure remote control, device management, and monitoring

Coming Soon

DLAP-411-Orin

Edge AI Inference Platform Powered by NVIDIA® Jetson AGX Orin™

- Linux® Ubuntu operating system
- Rich I/O fanless compact design
- Complete power control even when the system is unresponsive
- Wide variety of industrial I/O ports and visual inferencing capabilities
- Support 24/7 secure remote control, device management, and monitoring
- Remote control by Allxon Out-of-Band (OOB)

x86 Edge AI Platform

DLAP-8000 Series

9th Gen Intel® Xeon®, Core™ i7/i5/i3 Processor-Based Compact Industrial GPU Workstation

- Dual SODIMMs for up to 64GB DDR4 / ECC options
- 2x DP++, 1x DVI-I, 3x GbE, 4x COM, 8-ch DI, 8-ch DO, TPM 2.0
- 2x USB 3.1 Gen2, 1x USB 3.1 Gen1, 3x USB 2.0
- Up to 4 hot swappable 2.5" SATA 6 Gb/s tray with RAID 0/1/5/10 support, CFast, M.2 2280
- 1x Mini PCIe, 1x M.2 3042, 2x USIM

DLAP-4000 Series

8th/9th Generation Intel® Core™ i7/i5/i3 Processor-Based Embedded System supporting FHFL dual-width PEG slot

- NVIDIA® Quadro® PEG card support
- 2x DDR4 SO-DIMMs, up to 32GB
- 1x DVI, 1x HDMI, 1x DP (from CPU), additional display outputs from PEG cards
- 1x Mini PCIe slot for Wi-Fi/Bluetooth or LTE module
- 300W/500W Flex ATX PSU

DLAP-3000-CF Series

8th/9th Gen Intel® Core™ i7/i5/i3 Processor-Based Embedded System supporting MXM Graphics Module

- ADLINK MXM Graphics module support (Type A/B, up to 120W)
- 2x DDR4 SO-DIMMs, up to 64GB
- 6x DisplayPort (2 from CPU, 4 from MXM)
- 1x M.2 key E, 1x M.2 key B
- Reliable Molex type 12V DC-in connector

Media Display Solution

Take your digital signage to the next level with our Media Display Solution. It offers smooth and dynamic signage display with reliable performance and minimal latency. Utilizing its easy-to-use CMS SignageGO, you can create, manage, and display stunning signs with ease.

MDS-500 Series

Intel® Processor Based Fanless Media Player with SignageGO CMS

- 11th Gen. Intel® Core™ i5 CPU
- 4x independent displays with FHD/4K resolution
- Fanless, rugged design for 24/7 operation
- M.2 2280 SSD for up to 2TB
- DDR4 SODIMM for up to 64GB
- SignageGO simple and intuitive digital signage management software

intel. iRIS Xe GRAPHICS

High Energy Efficiency

Compact Size

Fanless Design

SignageGO

Simple and Intuitive Content management system

- Easy-to-use interface for easily creating and managing display programs
- Remote monitoring and management of multiple digital displays
- Automated content publishing with custom triggers
- 1-click batch uploading to multiple signage players
- Detailed display statistical reports

SignageGO

Unmatched Digital Signage Performance

4 Displays

Support 4 independent display with FHD/4K resolution.

High Energy Efficiency

Capable of driving four displays with reliable performance and minimal latency.

Effortless Management

Simple and Intuitive CMS to manage and monitor of multi digital displays.

Embedded Robotic Controllers

ADLINK ROSCube is an autonomous platform solution that integrates hardware and software components to provide a comprehensive and powerful robotic controller in a compact, ruggedized enclosure. It 's also designed to be highly modular, allowing developers to easily integrate additional components and peripherals to meet the specific needs of their applications. With its powerful processing capabilities, compatibility with high-quality cameras, and support for a wide range of sensors, the ADLINK ROSCube is an excellent platform for developing advanced robotic systems.

Embedded Robotic Controllers

NEW

RQX-59 Series

Performance Expandable Robotic Controller based on NVIDIA® Jetson AGX Orin ™

- Powerful AI computing for intelligent robotics development and AI computing for intelligent robotics development
- Excellent performance per watt with a power consumption as low as 40 W
- Ruggedized, secure connectivity with locking USB ports
- Comprehensive I/O for connecting a wide range of devices
- Time synchronization for both GMSL1/2 and FPD-Link III camera

RQX-580/58G

Performance Expandable Robotic Controller based on NVIDIA® Jetson™ AGX

- Powerful AI computing for intelligent robotics development
- Excellent performance per watt with power consumption as low as 30 W
- Ruggedized, secure connectivity with locking USB ports
- Comprehensive I/O for connecting a wide range of devices
- Time synchronization with GMSL2 camera

NPN-1B/2B

Compact Fanless Robotic Controller based on NVIDIA® Jetson™ NX

- Low power consumption (15W) and excellent per-watt performance
- Compact, durable and fanless design
- Comprehensive I/O for broad compatibility
- Reliable, lockable USB connectors

RQP-T33/35/37

Compact Fanless Robotic Controller based on Intel® 11th Gen Core Processor

- x86-64 mainstream architecture for ROS 2 development
- Ruggedized, secure connectivity with locking USB ports
- Integrated hard and soft real-time mechanism

RQI-53/55/57/58

Performance Expandable Robotic Controller based on Intel® 9th Gen Core Processor

- x86-64 mainstream architecture for ROS 2 development
- Comprehensive I/O for connecting a wide range of devices
- Ruggedized, secure connectivity with locking USB ports
- External PCIe Gen3 expansions with ruggedized cassette
- Integrated both hard and soft real-time mechanism

The Easiest Way to Develop EDGE Perception

ADLINK has partnered with Tier IV, an open source autonomous driving provider, to offer the ESK-Edge Perception Development Kit, an integrated turn-key solutions for autonomous driving applications.

The DevKit combines ADLINK RQX-58G robotic controller with Tier IV Automotive HDR Camera C1, while featuring camera perception functionality provided by Autoware*, and is specifically suited for autonomous driving applications requiring high-AI computing workloads with minimal power consumption.

Utilizing Tier IV's C1 camera, this Edge Perception Development kit provides users with a powerful GMSL2 controller package, which allows users to start building R&D environments with less time and effort, significantly reducing costs and shortening time-to-market.

PREFERRED PARTNER

TIER IV

ESK - Edge Perception Development Kit

RQX-58G

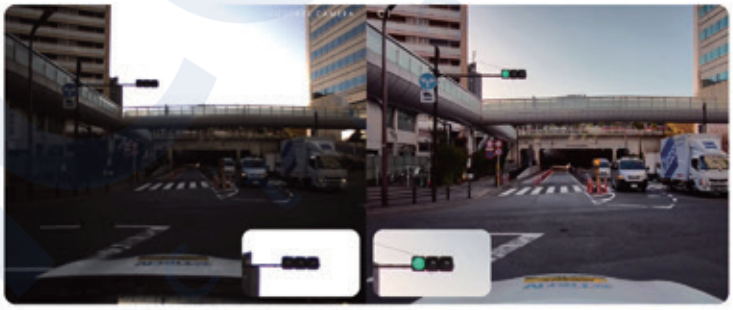
ADLINK Robotic Controller / AI-based Perception ECU

- Powerful AI computing for intelligent robotics development
- Excellent performance per watt with power consumption as low as 30W
- Ruggedized, secure connectivity with locking USB ports
- Comprehensive I/O for connecting to a wide range of devices
- Time synchronization with GMSL2 camera

Tier IV C1 Camera

- 2.5MP resolution, 120dB HDR, LED flicker mitigation
- Integrated ISP, on-board lens distortion correction
- GMSL2 direct connection, HW/SW triggering
- IP69K, -40 to 85°C operation, FuSa support up to ASIL B
- Autoware* compatible, with Linux kernel driver and ROS1/2 support

LED Flicker Mitigation



High Dynamic Range

High Sensitivity

*Autoware is a registered trademark of The Autoware Foundation.